

August 1998

# FDC6326L Integrated Load Switch

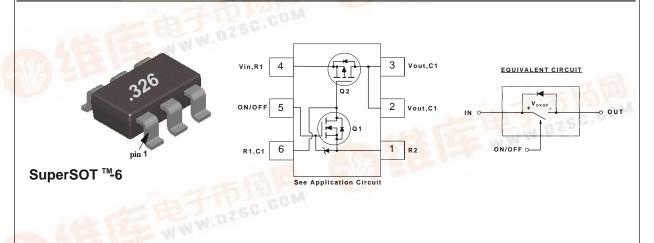
## **General Description**

This device is particularly suited for compact power management in portable electronic equipment where 3V to 20V input and 1.8A output current capability are needed. This load switch integrates a small N-Channel power MOSFET (Q1) which drives a large P-Channel power MOSFET (Q2) in one tiny SuperSOT<sup>TM</sup>-6 package.

### **Features**

- $V_{DROP}$ =0.20V @  $V_{IN}$ =12V,  $I_{L}$ =1.5A. $R_{DS(ON)}$  = 0.125  $\Omega$   $V_{DROP}$ =0.20V @  $V_{IN}$ =5V,  $I_{L}$ =1A. $R_{DS(ON)}$  = 0.20  $\Omega$ .
- SuperSOT<sup>TM</sup>-6 package design using copper lead frame for superior thermal and electrical capabilities.





Absolute Maximum Ratings T<sub>A</sub> = 25°C unless otherwise noted

Symbol	Parameter	FDC6326L	Units
V <sub>IN</sub>	Input Voltage Range	3 - 20	V
V <sub>ON/OFF</sub>	On/Off Voltage Range	2.5 - 8	V
I <sub>L</sub>	Load Current - Continuous (Note 1)	1.8	Α
	- Pulsed (Note 1 & 3)	5	
$P_{D}$	Maximum Power Dissipation (Note 2)	0.7	W
T <sub>J</sub> ,T <sub>STG</sub>	Operating and Storage Temperature Range	-55 to 150	
ESD	Electrostatic Discharge Rating MIL-STD-883D Human Body Model (100pf/1500Ohm)	6	kV
THERMA	L CHARACTERISTICS		
$R_{\theta JA}$	Thermal Resistance, Junction-to-Ambient (Note 2)	180	°C/W
$R_{\theta JC}$	Thermal Resistance, Junction-to-Case (Note 2)	60	°C/W

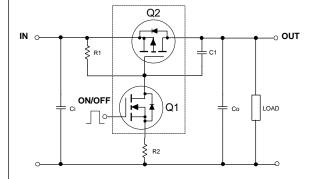
Electrical Characteristics (T <sub>A</sub> = 25°C unless otherwise noted)									
Symbol	Parameter	Conditions	Min	Тур	Max	Units			
OFF CHA	RACTERISTICS								
I <sub>FL</sub>	Forward Leakage Current	V <sub>IN</sub> = 20 V, V <sub>ON/OFF</sub> = 0 V			1	μΑ			
ON CHAR	ACTERISTICS (Note 3)								
$V_{DROP}$	Conduction Voltage Drop	$V_{IN} = 12 \text{ V}, \ V_{ON/OFF} = 3.3 \text{ V}, \ I_{L} = 1.5 \text{ A}$		0.15	0.2	V			
		$V_{IN} = 5 \text{ V}, \ V_{ONOFF} = 3.3 \text{ V}, \ I_{L} = 1 \text{ A}$		0.14	0.2				
R <sub>DS(ON)</sub>	Q <sub>2</sub> - Static On-Resistance	$V_{GS} = -12 \text{ V}, \ I_D = -1.9 \text{ A}$		0.095	0.125	Ω			
		$V_{GS} = -5 \text{ V}, I_{D} = -1.5 \text{ A}$		0.14	0.2				
I <sub>L</sub>	Load Current	$V_{DROP} = 0.125 \text{ V}, V_{IN} = 12 \text{ V}, V_{ON/OFF} = 3.3 \text{ V}$	1			Α			
		$V_{DROP} = 0.20 \text{ V}, V_{IN} = 5 \text{ V}, V_{ON/OFF} = 3.3 \text{ V}$	1						

#### Notes:

- 1.  $V_{IN}$ =20V,  $V_{ONOFF}$ =8V,  $T_A$ =25°C
- 2. R<sub>But</sub> is the sum of the junction-to-case and case-to-ambient thermal resistance where the case thermal reference is defined as the solder mounting surface of the drain pins. R<sub>Buc</sub> is guaranteed by design while R<sub>Buck</sub> is determined by the user's board design.
- 3. Pulse Test: Pulse Width  $\leq$  300 $\mu$ s, Duty Cycle  $\leq$  2.0%.

# FDC6326L Load Switch Application

# **APPLICATION CIRCUIT**



# **External Component Recommendation**

First select R2,  $100 - 1k\Omega$ , for Slew Rate control.

 $C1 \le 1000$ pF can be added in addition to R2 for further In-rush current control.

Then select R1 such that R1/R2 ratio maintains between 10 - 100. R1 is required to turn Q2 off.

For SPICE simulation, users can download a "FDC6326L.MOD" Spice model from Fairchild Web Site at www.fairchildsemi.com

# **Typical Electrical Characteristics** ( $T_A = 25$ $^{\circ}$ C unless otherwise noted )

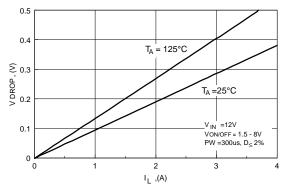


Figure 1. Conduction Voltage Drop Variation with Load Current.

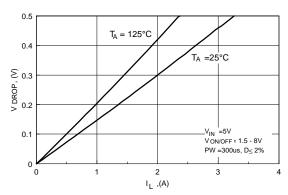


Figure 2. Conduction Voltage Drop Variation with Load Current.

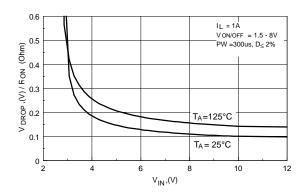


Figure 3. On-Resistance Variation with Input Voltage.

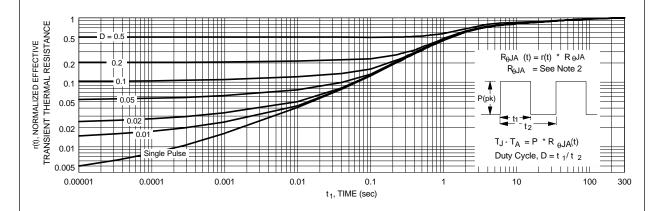
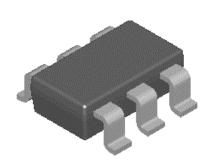


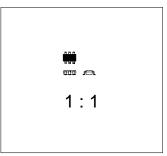
Figure 4. Transient Thermal Response Curve.

Thermal characterization performed on the conditions described in Note 2.



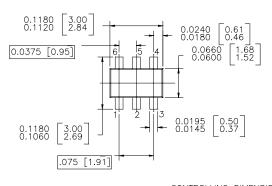
# SuperSOT™-6 (FS PKG Code 31, 33)

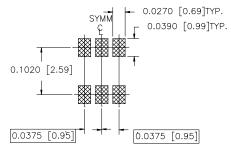




Scale 1:1 on letter size paper
Dimensions shown below are in:
inches [millimeters]

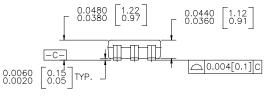
Part Weight per unit (gram): 0.0158

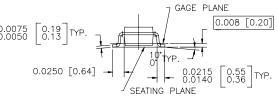




LAND PATTERN RECOMMENDATION

CONTROLLING DIMENSION IS INCH VALUES IN [ ] ARE MILLIMETERS





NOTES: UNLESS OTHERWISE SPECIFIED

1.0 STANDARD LEAD FINISH: 150 MICROINCHES 93.81 MICROMETERS) MINIMUM TIN / LEAD (SOLDER) ON COPPER.

2.0 NO JEDEC REGISTRATION AS OF JULY 1996

SUPER SOT 6 LEADS

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E<sup>2</sup>CMOS<sup>™</sup> PowerTrench<sup>™</sup>

FACT<sup>TM</sup> QS<sup>TM</sup>

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